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ARM, HP and Hynix join the Hybrid Memory Cube party

Work with Samsung and Micron for higher bandwidth

By [Lawrence Latif](#)

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INDUSTRY GIANTS ARM, HP and SK Hynix have joined the Hybrid Memory Cube Consortium (HMCC).

[Samsung](#) and Micron are already members of the HMCC, an organisation that pushes Hybrid Memory Cube technology. Now chip designer ARM, enterprise IT vendor HP and the second largest [DRAM](#) manufacturer SK Hynix have put their weight behind the technology by signing on with the HMCC.

The firms join IBM, Microsoft and Xilinx, who are working on drafting a specification for the next generation [memory technology](#). Hybrid Memory Cube technology is being promoted as a cost effective way to scale memory bandwidth in servers and network equipment.

Micron VP for DRAM marketing Robert Feurle said, "The strong collection of companies who have joined the consortium - representing a broad range of technology interests - reflects the perceived high value of HMC as the next standard for high-performance memory applications. With the addition of ARM, HP and SK hynix as developers, who will help to determine the specific features, the consortium is well positioned to provide a new open standard for next-gen electronics."

According to Micron, the HMCC should have a final interface specification for Hybrid Memory Cube by the end of 2012. Given that Samsung, Hynix and Micron are involved it is pretty obvious that the specification will see the light of day in

DRAM products sooner rather than later. μ

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